Silicon P Channel MOS Type (U-MOS-II) / Silicon Epitaxial Schottky Barrier Diode

**TENTATIVE** 

# TPCP8BA1

DC-DC Converter

- Combined Pch MOSFET and Schottky Diode into one Package.
- Low RDS (ON) and Low VF

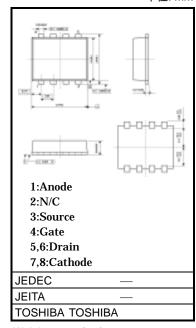
### Maximum Ratings (Ta = 25°C) MOSFET

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V <sub>DS</sub>	-20	V	
Gate-Source voltage		V <sub>GSS</sub>	±12	V	
Drain current	DC	I <sub>D</sub>	-1.3	Α	
	Pulse	I <sub>DP</sub> (Note 2)	-2.6	A	
Drain power dissipation		P <sub>D</sub> (Note 1)	1.0	W	
Channel temperature		T <sub>ch</sub>	150	°C	

## Maximum Ratings (Ta = 25°C) SCHOTTKY DIODE

Characteristics	Symbol	Rating	Unit
Maximum (peak) reverse voltage	$V_{RM}$	30	V
Reverse voltage	V <sub>R</sub>	25	V
Average forward current	IO	0.7	Α
Peak one cycle surge forward current (non-repetitive)	I <sub>FSM</sub>	4 (50 Hz)	А
Junction temperature	Tj	125	°C

#### 単位: mm



Weight: mg (typ)

#### Maximum Ratings (Ta = 25°C) MOSFET, DIODE COMMON

Characteristics	Symbol	Rating	Unit
Storage temperature	T <sub>stg</sub>	-55~125	°C
Operating temperature	T <sub>opr</sub> (Note 3)	-40~85	°C

Note 1: Mounted on FR4 board

(25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm<sup>2</sup>)

Note 2: The pulse width limited by max channel temperature.

Note 3: Operating temperature limited by max channel temperature and max junction temperature.

#### **Handling Precaution**

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing and use containers and other objects that are made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th}$  (ch-a) and the drain power dissipation PD vary according to the board material, board area, board thickness and pad area. When using this device, please take heat dissipation fully into account.

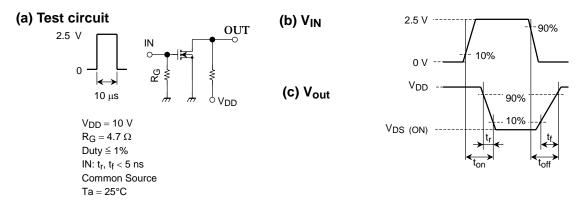
#### **MOSFET**

## **Electrical Characteristics (Ta = 25°C)**

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$		_	±1	μΑ
Drain-Source breakdown voltage		V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$	-20	_	_	V
		V (BR) DSX	$I_D = -1 \text{ mA}, V_{GS} = +12 \text{ V}$	-8	_	_	
Drain Cut-off curre	nt	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0$	_	_	-1	μА
Gate threshold vol	tage	V <sub>th</sub>	$V_{DS} = -3 \text{ V}, I_{D} = -0.1 \text{ mA}$	-0.5	_	-1.1	V
Forward transfer a	dmittance	Y <sub>fs</sub>	$V_{DS} = -3 \text{ V}, I_D = -0.65 \text{ A}$ (注 4)	1.3	2.7	_	S
Drain-Source ON resistance			I <sub>D</sub> = -0.65 A, V <sub>GS</sub> = -4 V (注 4)	_	140	180	
		R <sub>DS (ON)</sub>	$I_D = -0.65 \text{ A}, V_{GS} = -2.5 \text{ V}$ (注 4)	_	200	260	mΩ
			I <sub>D</sub> = -0.65 A, V <sub>GS</sub> = -2.0 V (注 4)	_	260	460	
Input capacitance		C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	370	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	73	_	pF
Output capacitance		C <sub>oss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	116	_	pF
Switching time	Turn-on time	ton	$V_{DD} = -10 \text{ V}, I_D = -0.65 \text{ A}$	_	33	_	- ns
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0$ ~ $-2.5 \text{ V}, R_{G} = 4.7 \Omega$	_	47	_	

Note 4: Pulse measurement

#### **Switching Time Test Circuit**



#### **Precaution**

 $V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D$  = -100  $\mu A$  for this product. For normal switching operation,  $V_{GS~(on)}$  requires higher voltage than  $V_{th}$  and  $V_{GS~(off)}$  requires lower voltage than  $V_{th}$ .

(Relationship can be established as follows:  $V_{GS}$  (off) <  $V_{th}$  <  $V_{GS}$  (on))

Please take this into consideration for using the device.

VGS recommended voltage of -2.5 V or higher to turn on this product.

# **Schottky Diode**

# **Electrical Characteristics** (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V <sub>F (1)</sub>	I <sub>F</sub> = 0.5 A	_	0.36	0.41	V
	V <sub>F (2)</sub>	I <sub>F</sub> = 0.7 A	_	0.40	0.45	V
Reverse current	I <sub>R</sub>	$V_R = 10V$	_	_	100	μА
Total capacitance	C <sub>T</sub>	V <sub>R</sub> = 10 V, f = 1 MHz	_	20	_	pF

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